103167-5 - ACTIVE

AMPMODU | AMPMODU Headers

TE Internal #: 103167-5 PCB Mount Header, Right Angle, Wire-to-Board, 16 Position, 2.54 mm [.1 in] Centerline, Fully Shrouded, Gold, Through Hole - Solder, AMPMODU Headers

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Connector System: Wire-to-Board

Number of Positions: 16

Number of Rows: 2

Centerline (Pitch): 2.54 mm [.1 in]

PCB Mount Orientation: Right Angle

Features

Product Type Features

Connector SystemWire-to-BoardHeader TypeFully ShroudedConnector & Contact Terminates ToPrinted Circuit Board



PCB Connector Assembly Type

PCB Mount Header

Configuration Features

| Connector Contact Load Condition | Fully Loaded |
|---|-------------------------------|
| Number of Positions | 16 |
| Number of Rows | 2 |
| PCB Mount Orientation | Right Angle |
| Electrical Characteristics | |
| Insulation Resistance | 5000 ΜΩ |
| Dielectric Withstanding Voltage (Max) | 750 Vrms |
| Body Features | |
| Connector Profile | Standard |
| Primary Product Color | Black |
| Contact Features | |
| Mating Square Post Dimension | .64 mm[.025 in] |
| PCB Contact Termination Area Plating Material Thickness | 2.54 – 5.08 μm[100 – 200 μin] |

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| Contact Mating Area Plating Material Thickness | .762 μm[30 μin] |
|--|----------------------------|
| Contact Shape & Form | Square |
| Contact Underplating Material | Nickel |
| PCB Contact Termination Area Plating Material | Tin-Lead |
| Contact Base Material | Phosphor Bronze |
| Contact Mating Area Plating Material | Gold |
| Contact Type | Pin |
| Contact Current Rating (Max) | 3 A |
| Termination Features | |
| Square Termination Post & Tail Dimension | .64 mm[.025 in] |
| Termination Post & Tail Length | 3.43 mm[.135 in] |
| Termination Method to Printed Circuit Board | Through Hole - Solder |
| Mechanical Attachment | |
| Mating Alignment Type | Polarization |
| Mating Retention | With |
| Mating Retention Type | Detent Window |
| Connector Mounting Type | Board Mount |
| Mating Alignment | With |
| PCB Mount Alignment | Without |
| PCB Mount Retention | Without |
| Housing Features | |
| Housing Material | Thermoplastic |
| Centerline (Pitch) | 2.54 mm[.1 in] |
| Dimensions | |
| PCB Thickness (Recommended) | 1.4 mm[.055 in] |
| Row-to-Row Spacing | 2.54 mm[.1 in] |
| Usage Conditions | |
| Housing Temperature Rating | Standard |
| Operating Temperature Range | -65 – 105 °C[-85 – 221 °F] |
| Operation/Application | |
| Solder Process Feature | Board Standoff |
| Circuit Application | Signal |
| | Signai |

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Industry Standards

| Agency/Standard | CSA |
|---|--|
| Approved Standards | CSA LR7189, UL E28476 |
| UL Flammability Rating | UL 94V-0 |
| Packaging Features | |
| Packaging Quantity | 176 |
| Packaging Type | Tray |
| EU RoHS Directive 2011/65/EU | Not Compliant |
| For compliance documentation, visit the product page on TE.com> | |
| EU ELV Directive 2000/53/EC | Not Compliant |
| China RoHS 2 Directive MIIT Order No 32, 2016 | Restricted Materials Above Threshold |
| EU REACH Regulation (EC) No. 1907/2006 | Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JAN 2022 |

Article Safe Usage Statements: Do not eat, drink or smoke when using this product. Wash thoroughly after

handling. Recycle if possible and dispose of the article by following all applicable governmental regulations relevant to your geographic location.

Halogen Content

Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free

Wave solder capable to 240°C

Product Compliance Disclaimer

Solder Process Capability

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

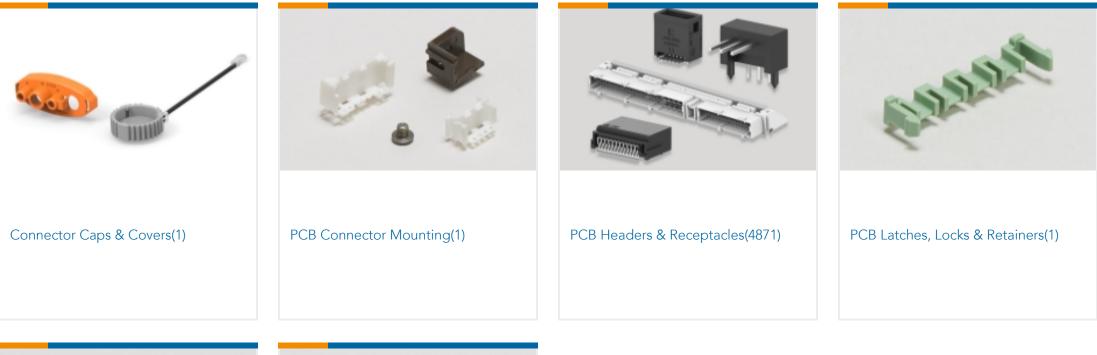
Compatible Parts

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Also in the Series AMPMODU Headers

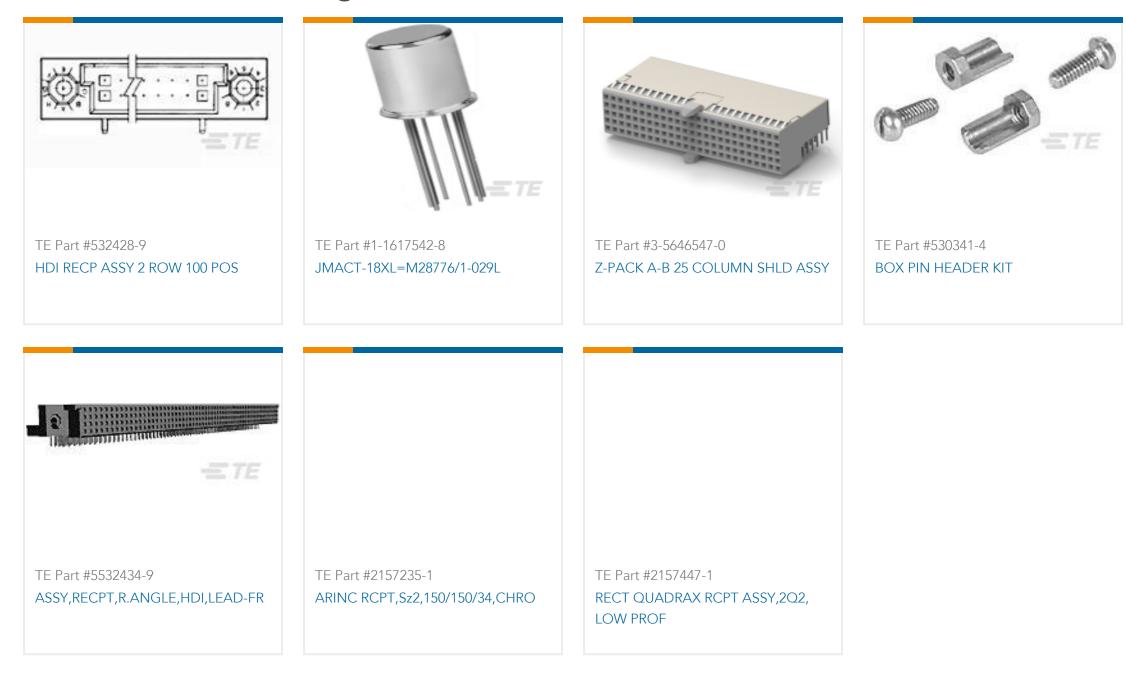


Connector Contacts(65)



| Wire-to-Board Connector Assemblies | Wire-to-Board |
|------------------------------------|---------------|
| & Housings(5) | |
| | |

Customers Also Bought



PCB Mount Header, Right Angle, Wire-to-Board, 16 Position, 2.54 mm [.1 in] Centerline, Fully Shrouded, Gold, Through Hole - Solder, AMPMODU Headers



Documents

Product Drawings 16 MODII HDR DRRA SHRD .100CL

English

CAD Files

Customer View Model ENG_CVM_CVM_103167-5_R.2d_dxf.zip

English

3D PDF

3D

Customer View Model

ENG_CVM_CVM_103167-5_R.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_103167-5_R.3d_stp.zip

English

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Product Specifications

Product Specification

English

Product Environmental Compliance

Product Compliance

English

Product Compliance

English